

L Number	Hits	Search Text	DB	Time stamp
1	11747	bga (ball with grid with array)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 01:03
2	5258	(bga (ball with grid with array)) and (lid top cover cap)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 01:04
3	2139901	semiconductor ic chip die (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 01:05
4	4890	((bga (ball with grid with array)) and (lid top cover cap)) and (semiconductor ic chip die (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 01:08
5	971	(ring retainer rim) and (((bga (ball with grid with array)) and (lid top cover cap)) and (semiconductor ic chip die (integrated adj circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 01:10
6	424255	heat with (sink element sink spreader radiate dissipate metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 01:12
7	361	(heat with (sink element sink spreader radiate dissipate metal)) and ((ring retainer rim) and (((bga (ball with grid with array)) and (lid top cover cap)) and (semiconductor ic chip die (integrated adj circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 01:12

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5	971	(ring retainer rim) and (((bga (ball with grid with array)) and (lid top cover cap)) and (semiconductor ic chip die (integrated adj circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 01:10
6	424255	heat with (sink element sink spreader radiate dissipate metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 01:34
7	361	(heat with (sink element sink spreader radiate dissipate metal)) and ((ring retainer rim) and (((bga (ball with grid with array)) and (lid top cover cap)) and (semiconductor ic chip die (integrated adj circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 01:12
8	1291	257/704	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 01:34
9	560	257/710	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 01:34
10	1637	257/704 257/710	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 01:34
11	1435	(257/704 257/710) and (semiconductor ic chip die (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 01:35
12	510	((257/704 257/710) and (semiconductor ic chip die (integrated adj circuit))) and (heat with (sink element sink spreader radiate dissipate metal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 01:35

13	457	(((257/704 257/710) and (semiconductor ic chip die (integrated adj circuit))) and (heat with (sink element sink spreader radiate dissipate metal))) not ((heat with (sink element sink spreader radiate dissipate metal)) and ((ring retainer rim) and (((bga (ball with grid with array)) and (lid top cover cap)) and (semiconductor ic chip die (integrated adj circuit)))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 01:36
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